



Material Content Data Sheet



Sales Product Name		BSS87 H6327		Issued		19. July 2018		
MA#		MA001048174						
Package		PG-SOT89-4-2		Weight*		50.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.026	0.05		513	
	non noble metal	tin	7440-31-5	0.007	0.01		132	
	inorganic material	silicon	7440-21-3	0.294	0.58	0.64	5809	6454
leadframe	inorganic material	silicon	7440-21-3	0.004	0.01		85	
	non noble metal	titanium	7440-32-6	0.022	0.04		427	
	non noble metal	chromium	7440-47-3	0.065	0.13		1282	
	non noble metal	copper	7440-50-8	21.522	42.54	42.72	425443	427237
wire	non noble metal	copper	7440-50-8	0.012	0.02	0.02	245	245
encapsulation	organic material	carbon black	1333-86-4	0.275	0.54		5430	
	plastics	epoxy resin	-	4.121	8.15		81457	
	inorganic material	silicondioxide	60676-86-0	23.076	45.63	54.32	456159	543046
leadfinish	non noble metal	tin	7440-31-5	0.811	1.60	1.60	16038	16038
plating	noble metal	silver	7440-22-4	0.353	0.70	0.70	6980	6980
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com